Commissioner for Patents
United States Patent and Trademark Office
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Date

: June 20, 2007

TO

: Director, Office of Patent Publication

FROM

: Office of Petitions

SUBJECT

: Withdrawal from Issue of Application No. 10/723,096

Applicant(s)

: John E. Kendall et al

Application No.

: 10/723,096

Filed

: November 26, 2003

The above-identified application has been assigned Patent No. 7,238,315 and an issue date of July 3, 2007.

It is hereby directed that this application be withdrawn from issue at the request of the applicant. Do not refund the issue fee.

The following erratum should be published in the Official Gazette if the above-identified application is published in the OG of July 3, 2007:

"All reference to Patent No. 7,238,315 to John E. Kendall et al of West Virginia for MOLDING COMPOUND appearing in the Official Gazette of July 3, 2007 should be deleted since no patent was granted."

Karen Creasy

Petitions Examiner Office of Petitions

cc:

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